ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INTERNATION CONNECTING	nposition De 5. IPC, Bannockt Pan-American co	c laration ourn, Illinois. A opyright conve	All rights reserved u ntions.	nder both	This docume level parts, th	ent is a declaration er	on of the substand acompasses all lo	es within the ma wer level materia	nufacturer liste als for which th	ed item. Note: if ne manufacturer	f the item is an as has engineering	ssembly with low responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Type			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
upplier Information												
Company name* Compan			ique ID	Unique			Inique ID Authority			Response Date*		
nsemi						2023-06-08						
Contact Name Title -			ct		1	Phone - Contact* Email - Contact*						
Product-Env-Stewards	Product Enviro Compliance				NA			Pro	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title			resentative Phone -			Phone - Represe	epresentative* En		Ema	Email - Representative*		
Product-Env-Stewards Pr			ro Compliance			NA Product-Env-Stewards@onsemi.com			om			
Requester Item Number Mfr Iten		Number Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	STK554	STK554U362A-E 3phase inverter		HIC		2023-06-08		VN2		16000.0	mg	Each
Ianufacturing Proccess Inform	nation					•	-					
Terminal Plating / Grid Array Material Terminal Base A		Alloy J	J-STD-020 MSI	ISL Rating Peak Pro		Process Body Temperature Max Time at Peak		at Peak Temp	erature Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed	0	CU Alloy	1	NA		0	С	30	se	conds 3		
omments												
or more information regarding mater	ial composition	please refer to	page 3									

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-ethers)					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexcess encompass all such components.Supplier cert as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided certification in this paragraph.If the Company	ted biphenyls and/or polybrominated dip of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ve relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr source of the Supplier's liability and the	henyl ethers (each a "RoHS restricted subs ndicate below which, if any, RoHS exempt ovides in this form using appropriate meth will rely on this certification in determinin ers in completing this form, and that Suppl num, itssuppliers have provided certificatio eement with respect to the identified part,t Company's remedies for issues that arise r	stance") in exce ion you believe ods to ensure i g the compliar ier may not ha ons regarding t he terms and co	ropean Union member states) of the part identifiess of the applicable quantity limit identified able may apply. If the part is an assembly with low is accuracy and that such information is true and ce of its products with European Union member independently verified such information. How heir contributions to the part, and those certifica onditions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of				
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for se	elected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7c-I Electrical and electronic c	omponents containing lead in a glass o	r ceramic other than dielectric ceramic	in capacitors,	e.g. piezoelectronic devices, or in a glass or c	eramic matrix compound.				
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.									
Supplier Digital Signature R	astislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Ceramic Substrate	4800.28	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6	F·	60.0035	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		236.6538	mg
			В	Nickel (Ni)	7440-02-0		8.1605	mg
			Supplier	Acrylic resins	Proprietary Data		3.3602	mg
			Supplier	Copper (Cu)	7440-50-8		322.5788	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		2.4001	mg
			Supplier	Aluminum (Al)	7429-90-5		4167.123	mg
Chip Parts	42.07	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0168	mg
			Supplier	Silver (Ag)	7440-22-4		1.7038	mg
			Supplier	Epoxy resins	129915-35-1		0.4333	mg
			Supplier	Bisphenol A, Epichlorohydrin polymer	25036-25-3, 25068- 38-6		0.0421	mg
			Supplier	Tin (Sn)	7440-31-5		1.3378	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.1022	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		8.6454	mg
			Supplier	Phenolic resins	Proprietary Data		0.1178	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0168	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0042	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		25.4818	mg
			В	Nickel (Ni)	7440-02-0		1.6239	mg
			А	Lead Oxide (PbO)	1317-36-8	7c	0.101	mg
			Supplier	Chromium Trioxide (Cr2O3)	1308-38-9		0.0042	mg
			Supplier	Copper (Cu)	7440-50-8		1.4388	mg
Die	33.1	mg	Supplier	Silicon (Si)	7440-21-3		33.1	mg
Die Attach	1.82	mg	Supplier	Silver (Ag)	7440-22-4		1.2385	mg
			Supplier	Other Epoxy resins	Proprietary Data		0.2732	mg
			Supplier	Tin (Sn)	7440-31-5		0.194	mg
			Supplier	Other Metal Oxide	Proprietary Data		0.069	mg
			В	Antimony (Sb)	7440-36-0		0.018	mg
			В	Antimony Pentoxide (Sb2O5)	1314-60-9		0.0273	mg
Heat Sink	1336.8	mg	Supplier	Silver (Ag)	7440-22-4		13.1006	mg

			Supplier	Copper (Cu)	7440-50-8	1323.6993	mg
Lead Frame	857.07	mg	Supplier	Tin (Sn)	7440-31-5	0.5142	mg
			Supplier	Copper (Cu)	7440-50-8	856.5558	mg
Mold Compound-Black	8813.31	mg		Brominated epoxy resin	proprietary data	176.2662	mg
			Supplier	Phenolic Resin	Proprietary Data	528.7986	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data	176.2662	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4	264.3993	mg
			Supplier	Fused Silica (SiO2)	60676-86-0	881.331	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2	616.9317	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7	6169.3164	mg
Plating	11.99	mg	Supplier	Tin (Sn)	7440-31-5	5.995	mg
			В	Nickel (Ni)	7440-02-0	5.995	mg
Solder Ball	44.97	mg	Supplier	Silver (Ag)	7440-22-4	1.3941	mg
			Supplier	Tin (Sn)	7440-31-5	43.2432	mg
			В	Antimony (Sb)	7440-36-0	0.0045	mg
			Supplier	Copper (Cu)	7440-50-8	0.3283	mg
Wire Bond - Al	58.59	mg	Supplier	Aluminum (Al)	7429-90-5	58.59	mg